

2023/10

ADEKA REMYLOP FL-326

Product Features

- One-component heat curing adhesive
- High thermal resistance
- High thermal conductivity

- Epoxy type (Halogen-free available)
- Low CTE (coefficient of thermal expansion)

Properties (uncured)

Viscosity / 25°C	0.5 rpm	140	Pa · s
	5 rpm	51	Pa · s
Thixotropic value	0.5 rpm/5 rpm	2.7	
Specific gravity		2.5	
Filler content		80	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	168	hrs
Shelf Life	≤ 5 °C	4	months
Viscosity / 25°C	≤ -18 °C	12	months

Cured Material Properties

Glass transition temperature	TMA	172	°C
	DMA	230	°C
Hardness	ShoreD	> D80	
Storage modulus/ 25°C	DMA	14.4	GPa
Coefficient of linear expansion	α_1	3	ppm
	α_2	78	ppm
Thermal conductivity	Transient hot wire method	3	W/m · K

DSC : SH DCS6220 25 – 300 °C (10 °C/min)

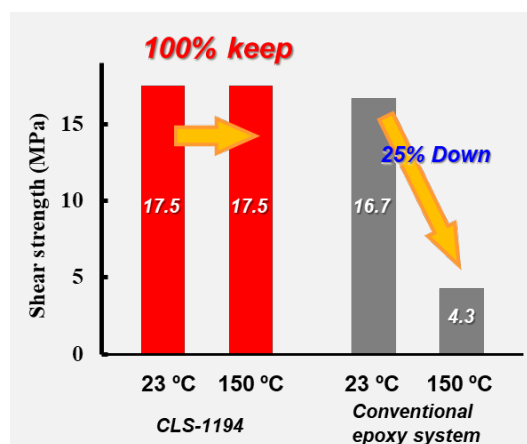
DMA : TA RSA-G2 25 – 300 °C (10 °C/min),
curing condition ; 180 °C × 1 hr

TMA : SH TMA/SS6100 25 – 300 °C (5 °C/min),
curing condition ; 180 °C × 1 hr

Recommended Curing Conditions

150	°C	1	hr
180		0.5	hr

Adhesion (Based on CLS-1194)



Fe/Fe Shear adhesion test (180 °C × 1 hr)

Usage

[Storage] Store in a sealed container at temperature below 5 °C (-18 °C recommended)

[Breaking the seal] To prevent moisture condensation, please bring the product to room temperature before opening the package.

[Curing] The adhesive must be heated sufficiently to reach the curing temperature. Curing conditions vary depending on the thermal capacity of the adherend and surrounding parts, the method of use, and the amount of coating applied.

[Disposal] Please refer to SDS for proper treatment.

[Others] Please contact us at the following

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